

RD Number: RD104

RD Title: TB67S511FTAG Evaluation circuit BOM

| Item No. | Designator | Quantity | Value | Part Number | Manufacturer | Description | Package | Not Mount |
|----------|------------|----------|----------------|-------------|--------------|------------------------|---------|-----------|
| 1 | C_VCC | 1 | 0.1μF 100V | — | — | Chip capacitor | | |
| 2 | C_VM2 | 1 | 0.1μF 100V | — | — | Chip capacitor | | |
| 3 | C_VRFA | 1 | 0.1μF 100V | — | — | Chip capacitor | | |
| 4 | C_VRFB | 1 | 0.1μF 100V | — | — | Chip capacitor | | |
| 5 | C_OAP | 0 | 0.1μF 100V | — | — | Chip capacitor | | ✓ |
| 6 | C_OAM | 0 | 0.1μF 100V | — | — | Chip capacitor | | ✓ |
| 7 | C_OBM | 0 | 0.1μF 100V | — | — | Chip capacitor | | ✓ |
| 8 | C_OBP | 0 | 0.1μF 100V | — | — | Chip capacitor | | ✓ |
| 9 | C_VM1 | 1 | 100μF 50V | — | — | Electrolytic capacitor | | |
| 10 | | 0 | Socket pin | — | — | Socket pin | | ✓ |
| 11 | C_VDD | 1 | 10μF 25V | — | — | Electrolytic capacitor | | |
| 12 | | 0 | Socket pin | — | — | Socket pin | | ✓ |
| 13 | C_OSCM | 1 | 270pF 1000V | — | — | Chip capacitor | | |
| 14 | | 0 | 270pF | — | — | Ceramic capacitor | | ✓ |
| 15 | | 0 | Socket pin | — | — | Socket pin | | ✓ |
| 16 | CON1 | 1 | Connector 4P | — | — | Connector 4P-2.5 | | |
| 17 | OSCM | 1 | Check terminal | — | — | Check terminal | | |
| 18 | OUT_A- | 1 | Check terminal | — | — | Logic pin | | |
| 19 | OUT_A+ | 1 | Check terminal | — | — | Logic pin | | |
| 20 | OUT_B- | 1 | Check terminal | — | — | Logic pin | | |
| 21 | OUT_B+ | 1 | Check terminal | — | — | Logic pin | | |
| 22 | RSA | 1 | Check terminal | — | — | Check terminal | | |
| 23 | RSB | 1 | Check terminal | — | — | Check terminal | | |
| 24 | VCC | 1 | Check terminal | — | — | Check terminal | | |
| 25 | VDD | 1 | Check terminal | — | — | Logic pin | | |
| 26 | VM | 1 | Check terminal | — | — | Logic pin | | |

| | | | | | | | | |
|----|---------|---|---------------------|---|---|-----------------|--|---|
| 27 | VREFA | 1 | Check terminal | – | – | Check terminal | | |
| 28 | VREFB | 1 | Check terminal | – | – | Logic pin | | |
| 29 | IN_A1 | 1 | Check terminal | – | – | Check terminal | | |
| 30 | IN_A2 | 1 | Check terminal | – | – | Check terminal | | |
| 31 | PHASE_A | 1 | Check terminal | – | – | Check terminal | | |
| 32 | PHASE_B | 1 | Check terminal | – | – | Check terminal | | |
| 33 | IN_B1 | 1 | Check terminal | – | – | Check terminal | | |
| 34 | IN_B2 | 1 | Check terminal | – | – | Check terminal | | |
| 35 | STANDBY | 1 | Check terminal | – | – | Check terminal | | |
| 36 | GND | 1 | Check terminal | – | – | Logic pin | | |
| 37 | GND | 1 | Check terminal | – | – | Logic pin | | |
| 38 | GND | 1 | Check terminal | – | – | Logic pin | | |
| 39 | GND | 1 | Check terminal | – | – | Logic pin | | |
| 40 | GND | 1 | Check terminal | – | – | Logic pin | | |
| 41 | GND | 1 | Check terminal | – | – | Logic pin | | |
| 42 | GND | 1 | Check terminal | – | – | Logic pin | | |
| 43 | JP_VRF1 | 1 | Pin header 2P | – | – | Jumper | | |
| 44 | | 1 | Jumper socket | – | – | Jumper Short | | |
| 45 | JP_VRF2 | 1 | Pin header 2P | – | – | Jumper | | |
| 46 | | 1 | Jumper socket | – | – | Jumper Short | | |
| 47 | JP_VCC | 1 | Pin header 2P | – | – | Jumper | | |
| 48 | | 1 | Jumper socket | – | – | Jumper Short | | |
| 49 | R_MOUT | 0 | 100k Ω 0.25W | – | – | Leaded resistor | | ✓ |
| 50 | | 0 | Socket pin | – | – | Socket pin | | ✓ |
| 51 | R_OSCM | 1 | 5.1k Ω 0.25W | – | – | Chip resistor | | |
| 52 | | 0 | Not mount | – | – | Leaded resistor | | ✓ |
| 53 | | 0 | Socket pin | – | – | Socket pin | | ✓ |
| 54 | R_VRF1 | 2 | Socket pin | – | – | Socket pin | | |
| 55 | | 0 | Not mount | – | – | Leaded resistor | | ✓ |
| 56 | R_VRF2 | 2 | Socket pin | – | – | Socket pin | | |
| 57 | | 0 | Not mount | – | – | Leaded resistor | | ✓ |
| 58 | R_RSA | 1 | 0.22 Ω 1W | – | – | Chip resistor | | |
| 59 | R_RSB | 1 | 0.22 Ω 1W | – | – | Chip resistor | | |
| 60 | IN_A1 | 1 | Pin header 3P | – | – | Jumper | | |

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